SEC

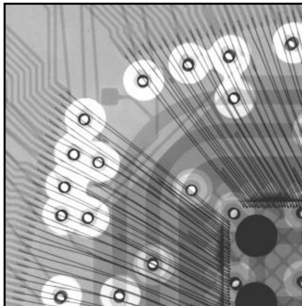
Semiconductor Packaging Application

Application:

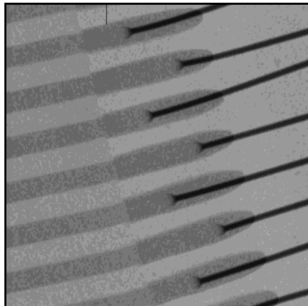
- Production Line – 2D Inspection
  - Bonding Wire (Au/Cu), Bump / Void Inspection
- Quality Assurance – 3D CT Analysis
  - TSV, Bump Delamination, Multi-Chip Packaging
  - 3D Packaging

Systems:

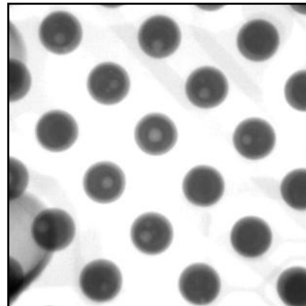
- **X-eye SF160A (2D) / SF160ACT (3D)**
- X-eye 5000BTS
- X-eye 3000A
- X-eye Micro CT



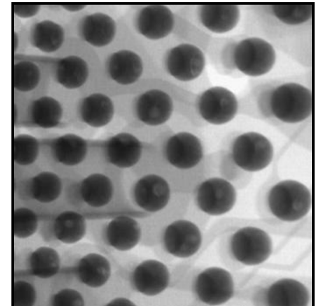
Bonding Wire (2D)



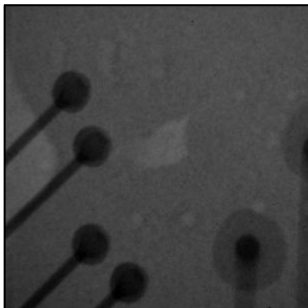
Bonding Wire (2D)



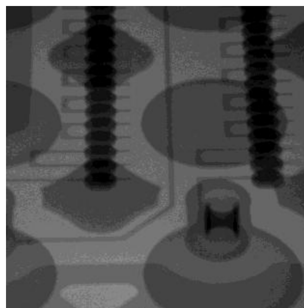
Bump Void



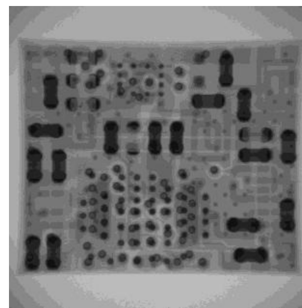
Bump Void – Tilt View



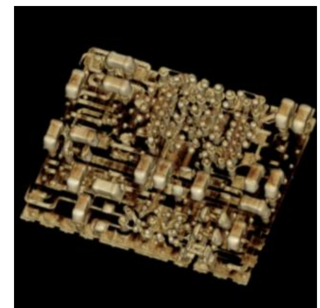
Epoxy Void



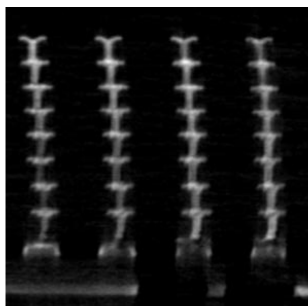
Bump



SiP – 2D

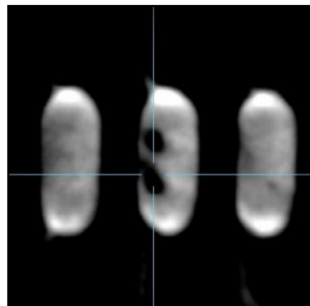


SiP – 3D CT

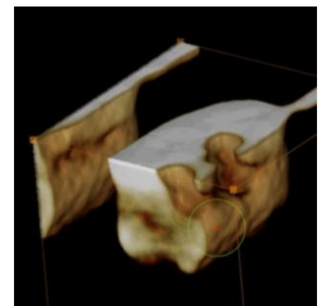


TSV Stack – Slice View

TSV Stack – 3D View



Cu Pillar – Slice View



Cu Pillar – 3D View

SEC e-beam pioneer

SEC CO., LTD.
415 Factory World, 332-2 Woncheon-Dong
Suwon, South Korea 443-758
www.seceng.co.kr/eng

Tel: +82-31-215-7341
Fax: +82-31-215-7343
Email: sales@seceng.co.kr

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